ALPHA & OMEGA SEMICONDUCTOR

AOL1422
N-Channel Enhancement Mode Field Effect Transistor

General Description

The AOL1422 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is ESD protected and it is suitable for use in load switching and general purpose applications.

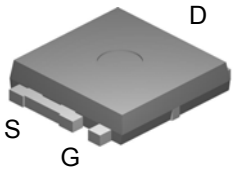
-RoHS Compliant
-Halogen and Antimony Free Green Device*

Features

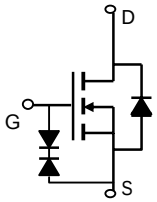
V_{DS} (V) = 30V
I_D = 85A (V_{GS} = 10V)
$R_{DS(ON)}$ < 3.7mΩ (V_{GS} = 10V)
$R_{DS(ON)}$ < 5.4mΩ (V_{GS} = 4.5V)

Rg,Ciss,Coss,Crss Tested

Ultra SO-8™ Top View



Bottom tab connected to drain



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [B,H]	T_C=25°C	I_D	85	A
	T_C=100°C		85	
Pulsed Drain Current [C]		I_{DM}	150	
Continuous Drain Current [G]	T_A=25°C	I_{DSM}	19	
	T_A=70°C		15	
Power Dissipation [B]	T_C=25°C	P_D	100	W
	T_C=100°C		50	
Power Dissipation [A]	T_A=25°C	P_{DSM}	2.08	
	T_A=70°C		1.3	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	19.6	25	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		50	60	°C/W
Maximum Junction-to-Case [D]	Steady-State	$R_{\theta JC}$	0.9	1.5	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±16V			10	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1	1.7	3	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	150			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A		3	3.7	mΩ
		T_J=125°C		4.2	5.2	
		V_{GS}=4.5V, I_D=20A		4.4	5.4	
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A		71		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.69	1	V
I_S	Maximum Body-Diode Continuous Current				85	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		5450	6800	pF
C_{oss}	Output Capacitance			760		pF
C_{rss}	Reverse Transfer Capacitance			540		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		1	1.5	Ω
SWITCHING PARAMETERS						
Q_g (10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=20A		84	112	nC
Q_g (4.5V)	Total Gate Charge			42	56	nC
Q_{gs}	Gate Source Charge			12		nC
Q_{gd}	Gate Drain Charge			21		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=0.75Ω, R_{GEN}=3Ω		13		ns
t_r	Turn-On Rise Time			9.8		ns
$t_{D(off)}$	Turn-Off DelayTime			49		ns
t_f	Turn-Off Fall Time			16		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, dI/dt=100A/µs		42	56	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, dI/dt=100A/µs		31		nC

A: The value of $R_{\theta JA}$ is measured with the device in a still air environment with T_A =25°C. The power dissipation P_{DSM} and current rating I_{DSM} are based on $T_{J(MAX)}$=150°C, using steady state junction-to-ambient thermal resistance.

B. The power dissipation P_D is based on $T_{J(MAX)}$=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C. The SOA curve provides a single pulse rating.

G. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

H. The maximum current rating is limited by bond-wires.

* This device is guaranteed green after date code 8P11 (June 1 ST 2008)

Rev3: Jul 2008

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

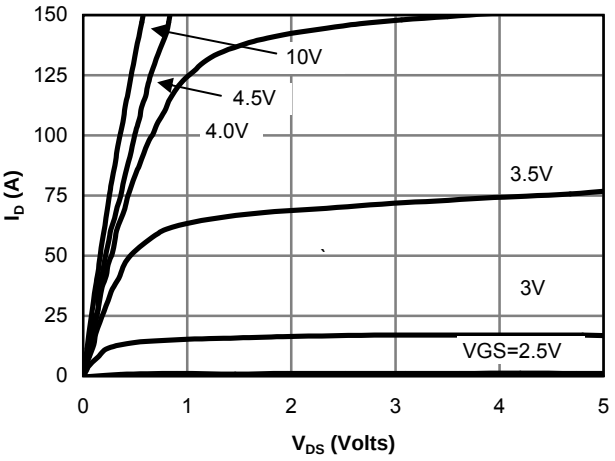


Figure 1: On-Region Characteristics

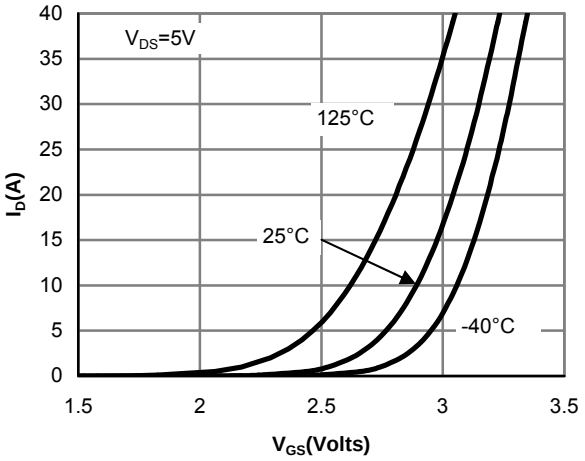


Figure 2: Transfer Characteristics

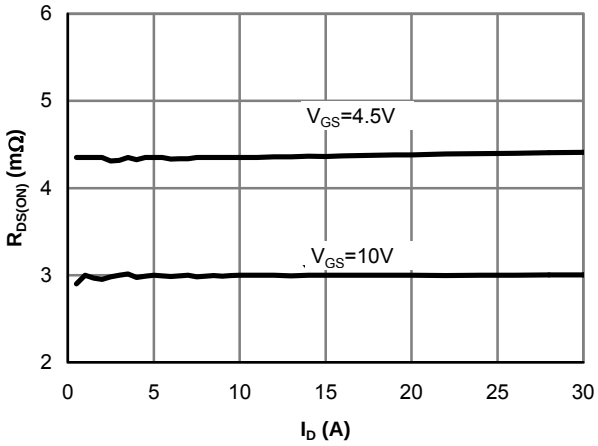


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

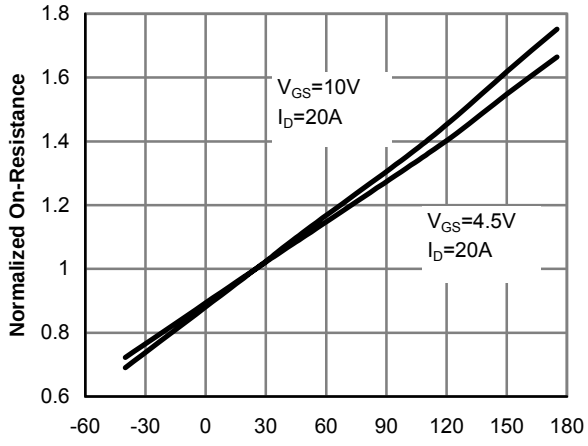


Figure 4: On-Resistance vs. Junction Temperature

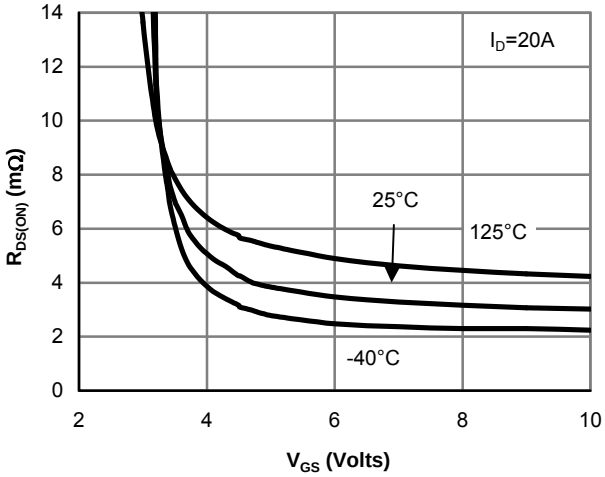


Figure 5: On-Resistance vs. Gate-Source Voltage

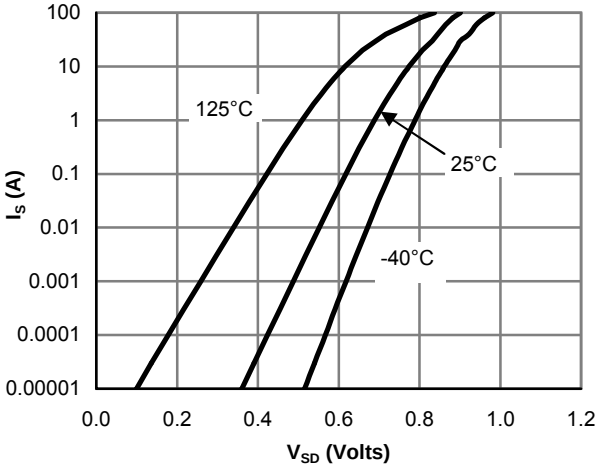


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

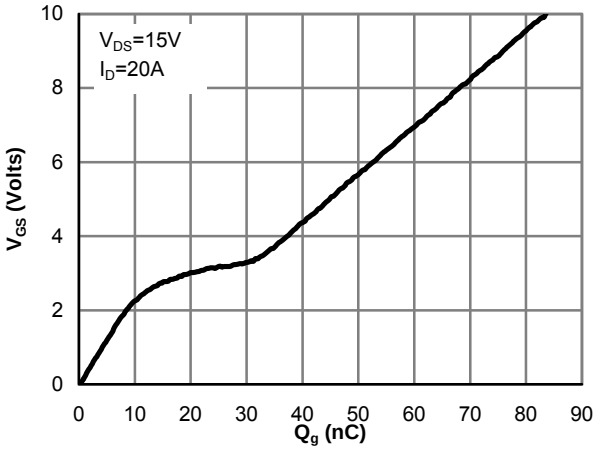


Figure 7: Gate-Charge Characteristics

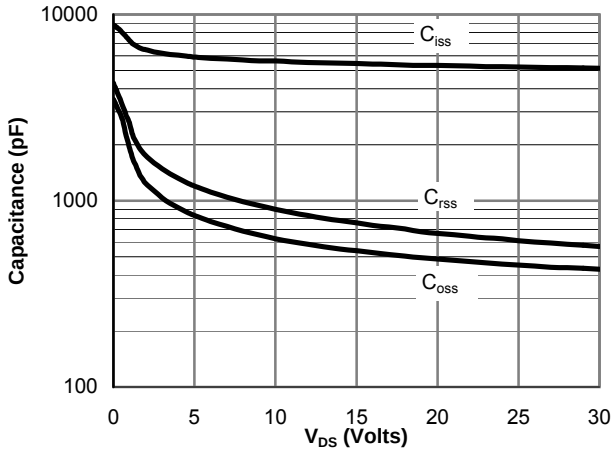


Figure 8: Capacitance Characteristics

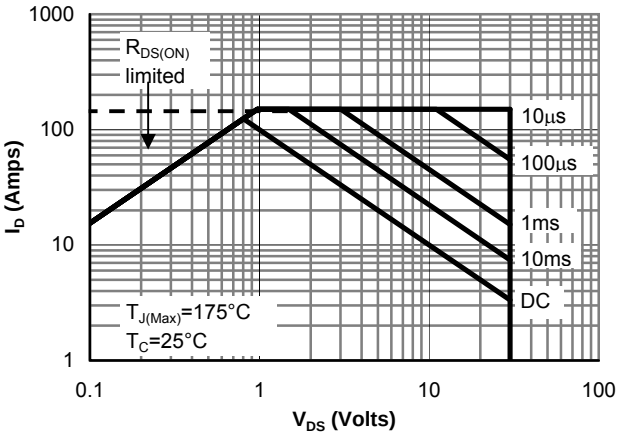


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

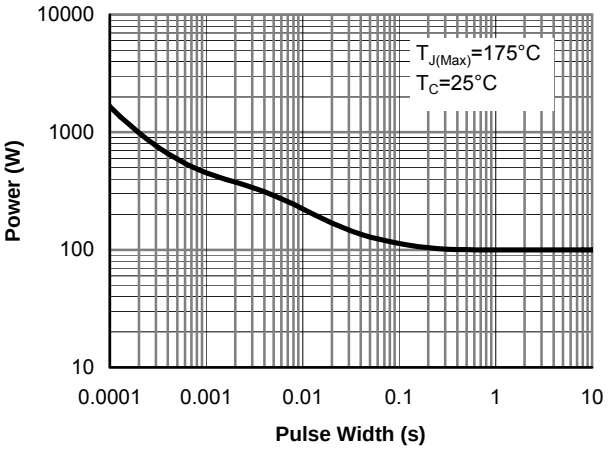


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

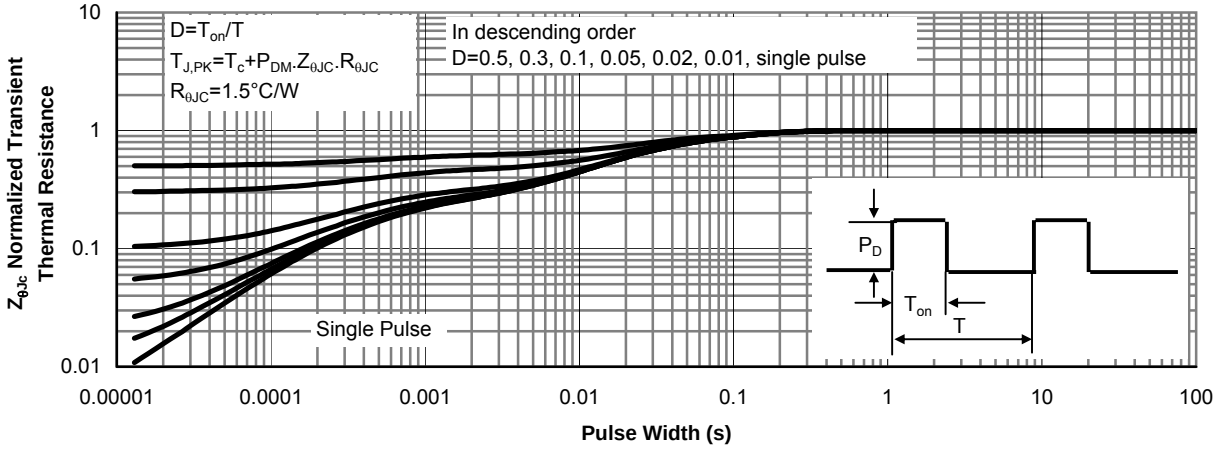


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

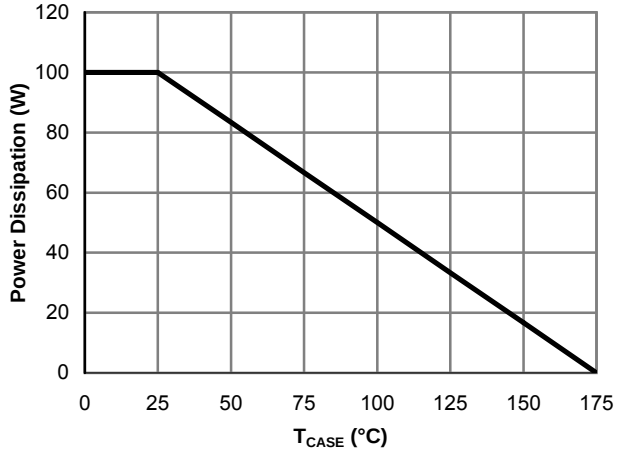


Figure 12: Power De-rating (Note B)

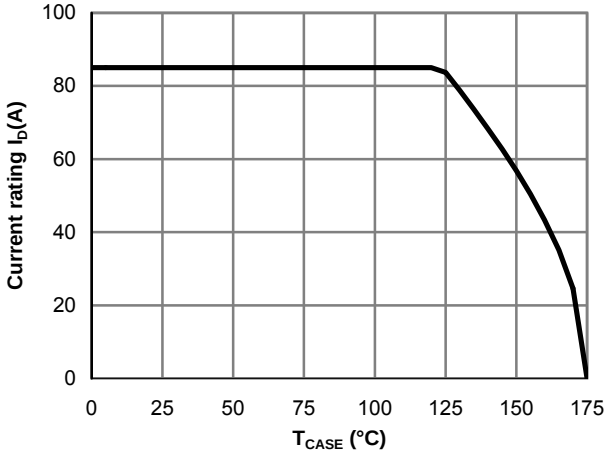


Figure 13: Current De-rating (Note B)

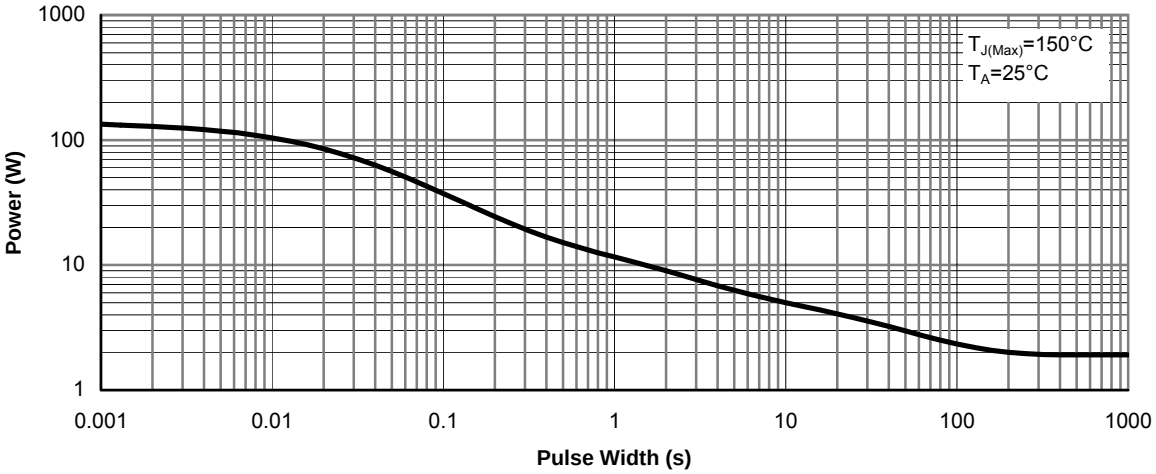


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note G)

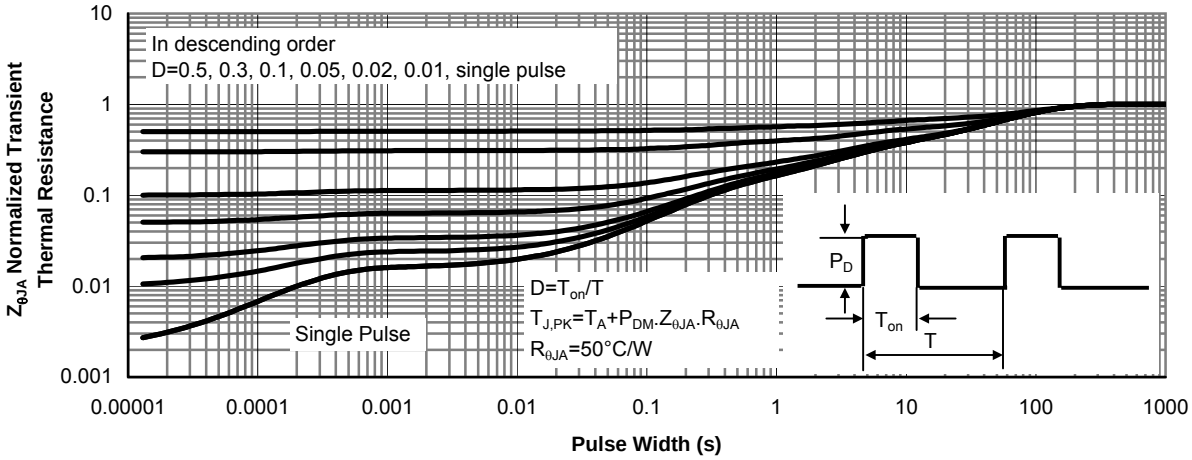
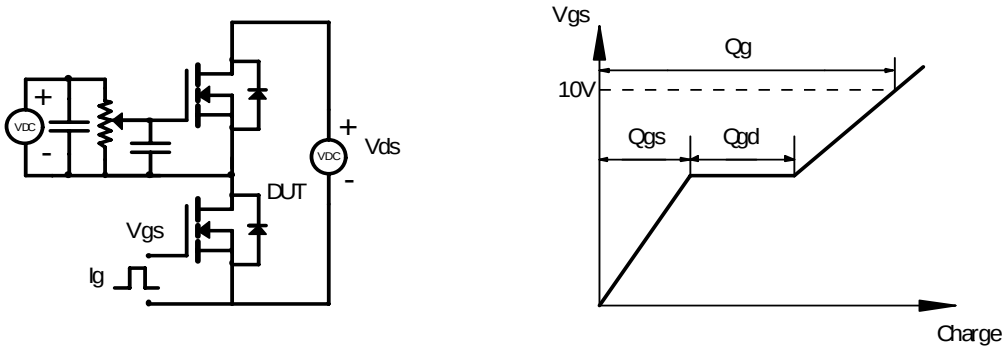
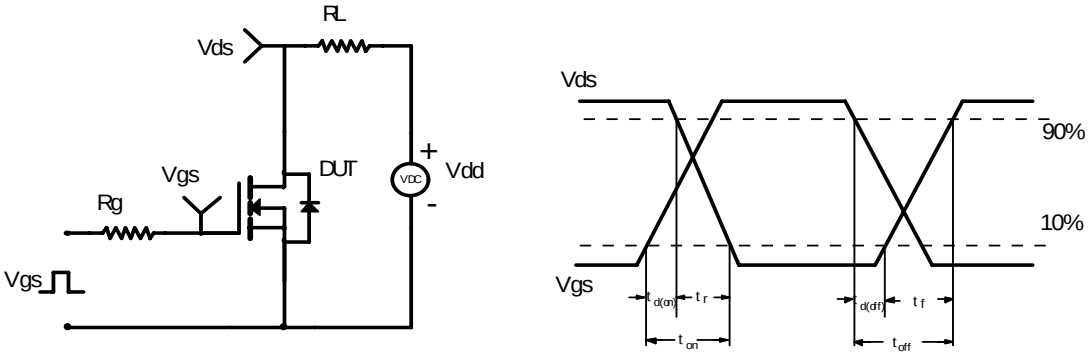


Figure 15: Normalized Maximum Transient Thermal Impedance (Note G)

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms